



Call for Papers

NordPac Conference

June 9 – 11, 2026

Stockholm, Sweden

Jointly arranged by:
IMAPS Nordic
IEEE EPS Nordic

We are proud to announce that the NordPac 2026 conference will be held in Stockholm, Sweden. This is a perfect opportunity for you to present your revolutionary work within the field of microelectronic packaging while enjoying the normally beautiful weather in Stockholm in June.

Abstract submission – Extended deadline

We hereby invite you to prepare an abstract for the conference. For NordPac 2026 we have expanded the possibilities for how you want to present your work. We will open three submission tracks:

- **Track 1** will require a **full paper submission** (4-6 pages). Accepted papers will be submitted for inclusion into IEEE Xplore subject to meeting IEEE Xplore's scope and quality requirements. (<http://ieeexplore.ieee.org/>).
- **Track 2** will only require an **extended abstract** (1-2 pages) and will only be published in the conference proceedings.
- **Track 3** is reserved for **commercial white papers** (1-4 pages) and will only be published in the conference proceedings. Presentations from all three tracks can appear in the same technical session.

The abstract submission **deadline for all three tracks is January 31st, 2026**.

Acceptance will be given within February 28th. After this, the three tracks follow different submission deadlines as indicated in the table below.

For full instructions on how to submit your paper and information on review process flow, please go to www.nordpac.org

Summary of deadlines

Conference portal open for submission	October 2025
Abstract submission	February 14th, 2026
Feedback on abstract	February 28 th , 2026
Track 1 – Full paper submission	April 30 th , 2026
Track 2 – Extended abstract submission	May 15 th , 2026
Track 3 – Commercial white paper submission	May 15 th , 2026
Notification of acceptance of all submissions	June 1 st , 2026

President:
Heidi Lundén
SCHOTT Primoceler Oy
Vesiroineekatu 3
33720 Tampere, Finland
tel. +358 40 080 7616
heidi.lunden@schott.com

Vice President:
Daniel Nilsen Wright, PhD
SINTEF Digital
MinaLab.
Gaustadaleen 23
NO - 0373 Oslo, Norway
Tel: +4793441038
daniel.nilsen.wright@sintef.no

Secretary:
Markku Lahti
VTT Technical Research Centre of Finland
Kaitoväylä 1, P.O. Box 1100,
FI-90571 Oulu, Finland
Tel: +358 (0)407051262
markku.lahti@vtt.fi
secretary@imapsnordic.org

Treasurer:
Anders E. Petersen
Oticon
Kongebakken 9,
DK-2765 Smørum, Denmark
Tel: +45 3913 8227
andp@demant.com
treasurer@imapsnordic.org

Board members:
Hoang Vu Nguyen
University of South-Eastern Norway
Raveien 215, 3184 Borre
Norway
Tel: +358 400 687261
Hoang.V.Nguyen@usn.no

Dag Andersson
RISE
P.O. Box 104, SE-431 22 Mölndal,
Sweden
Tel: +46 (0)31-706 61 41
dag.andersson@ri.se

Rajan Ambat
Technical University of Denmark
DK 2800 Kgs. Lyngby, Denmark
Tel: +45 - 45252181
ram@mek.dtu.dk

Jiantong Li, Associate professor
KTH Royal Institute of Technology
SE-100 44 Stockholm
Sweden
+46 8 790 60 00
jiantong@kth.se

Markus Peil
Tampere University, Finland
+358 (0)294 5211
markus.peil@tuni.fi

Firehun T. Dullo, PhD
SINTEF Digital
MinaLab.
Gaustadaleen 23
NO - 0373 Oslo, Norway
+47 45052998
firehun.t.dullo@sintef.no

Topics

Proposed topics of microelectronics and packaging include:

Optoelectronics	Harsh environment applications
Photonics and Photonic packaging	Packaging for sensors & systems
Advanced Packaging	Electronics Reliability & Quality
Materials & Processes	Medical electronics
Thermal management	Wearable electronics
Green Technologies	Printed electronics

About the conference

The event brand NordPac was introduced in Gothenburg in 2017 as a collaboration between IMAPS Nordic and IEEE Electronics Packaging Society (EPS) Nordic. NordPac prides itself on being a small and specialised conference where networking is easy.

Reviewed papers will be submitted for publication in IEEE-Xplore with a licence to publish. The Licence allows the author to retain the copyright for the work and can publish it six months after the work has been published in IEEE-Xplore.

For the latest information about the conference and the exhibition, visit our homepage at www.nordpac.org or email to info@nordpac.org.

Preliminary program includes:

- **Workshops / Short courses**
- **IEEE Distinguished Lecture**
- **Keynotes**
- **Technical sessions**
- **Exhibition and Exhibitor presentations**
- **Tour of the Electrum Laboratories**
- **Complementary lunch, welcome reception and conference dinner**



LinkedIn @IMAPSNordic



Main organiser



Technical co-sponsor

President:
Heidi Lundén
SCHOTT Primoceler Oy
Vesiroineekatu 3
33720 Tampere, Finland
tel. +358 40 080 7616
heidi.lunden@schott.com

Vice President:
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RISE
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ram@mek.dtu.dk

Jiantong Li, Associate professor
KTH Royal Institute of Technology
SE-100 44 Stockholm
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